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(12) **United States Design Patent**
Choi et al.

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(54) **LIGHT EMITTING DIODE PACKAGE**

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(*) Notice: This patent is subject to a terminal disclaimer.

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(52) **U.S. Cl.**
USPC **D13/180**

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CPC ... H01L 25/167; H01L 25/0753; H01L 27/15; H01L 27/156; H01L 31/02; H01L 33/00; H01L 33/04; H01L 33/08; H01L 33/10; H01L 33/20; H01L 33/38; H01L 33/42; H01L 33/48; H01L 33/483; H01L 33/486; F21S 43/14; F21S 43/145; F21S 43/15; F21S 43/20
See application file for complete search history.

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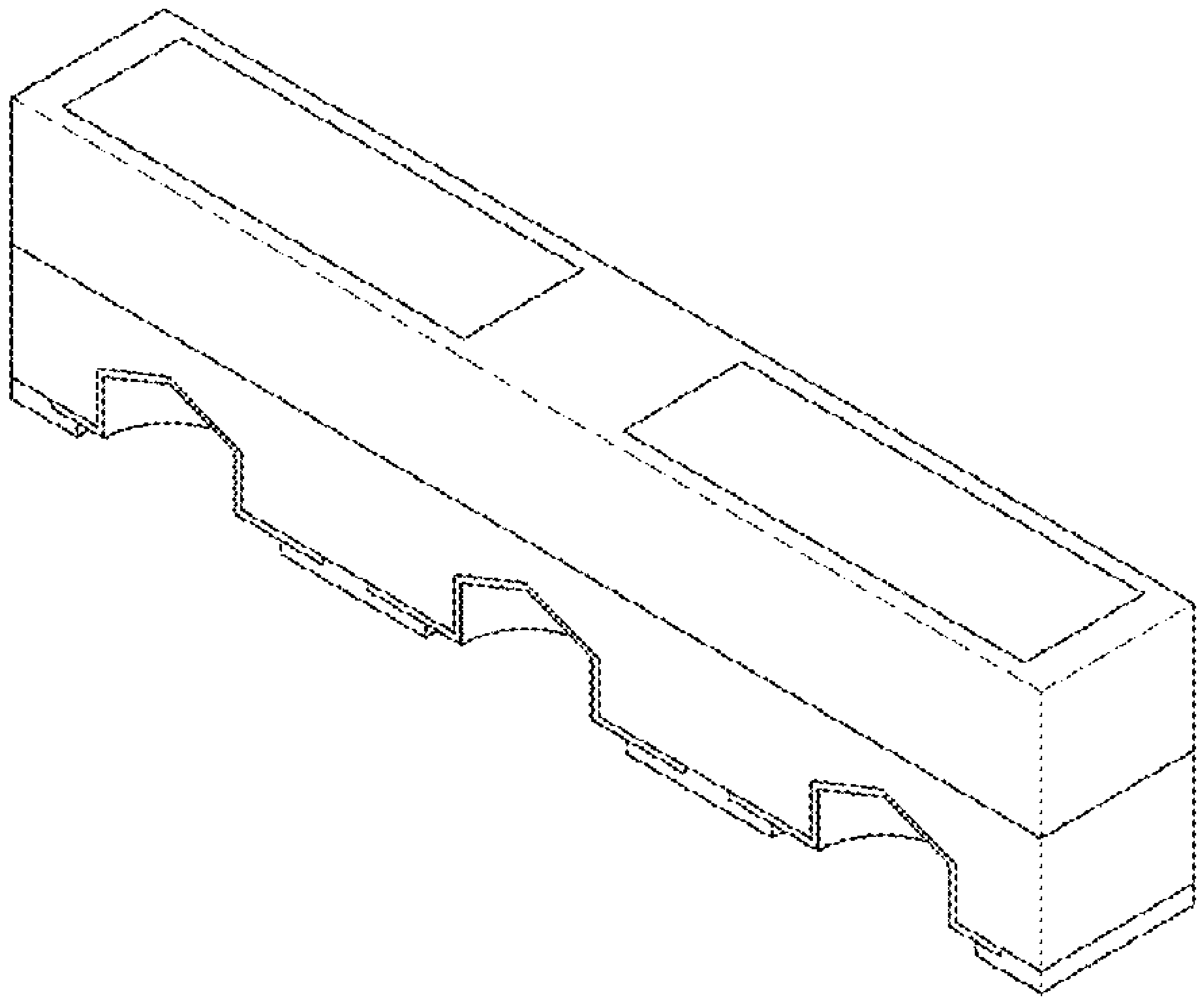
(57) **CLAIM**

The ornamental design for light emitting diode package, as shown and described.

DESCRIPTION

1. Light emitting diode package
1.1 : Perspective
1.2 : Front
1.3 : Back
1.4 : Left
1.5 : Right
1.6 : Top
1.7 : Bottom

1 Claim, 7 Drawing Sheets



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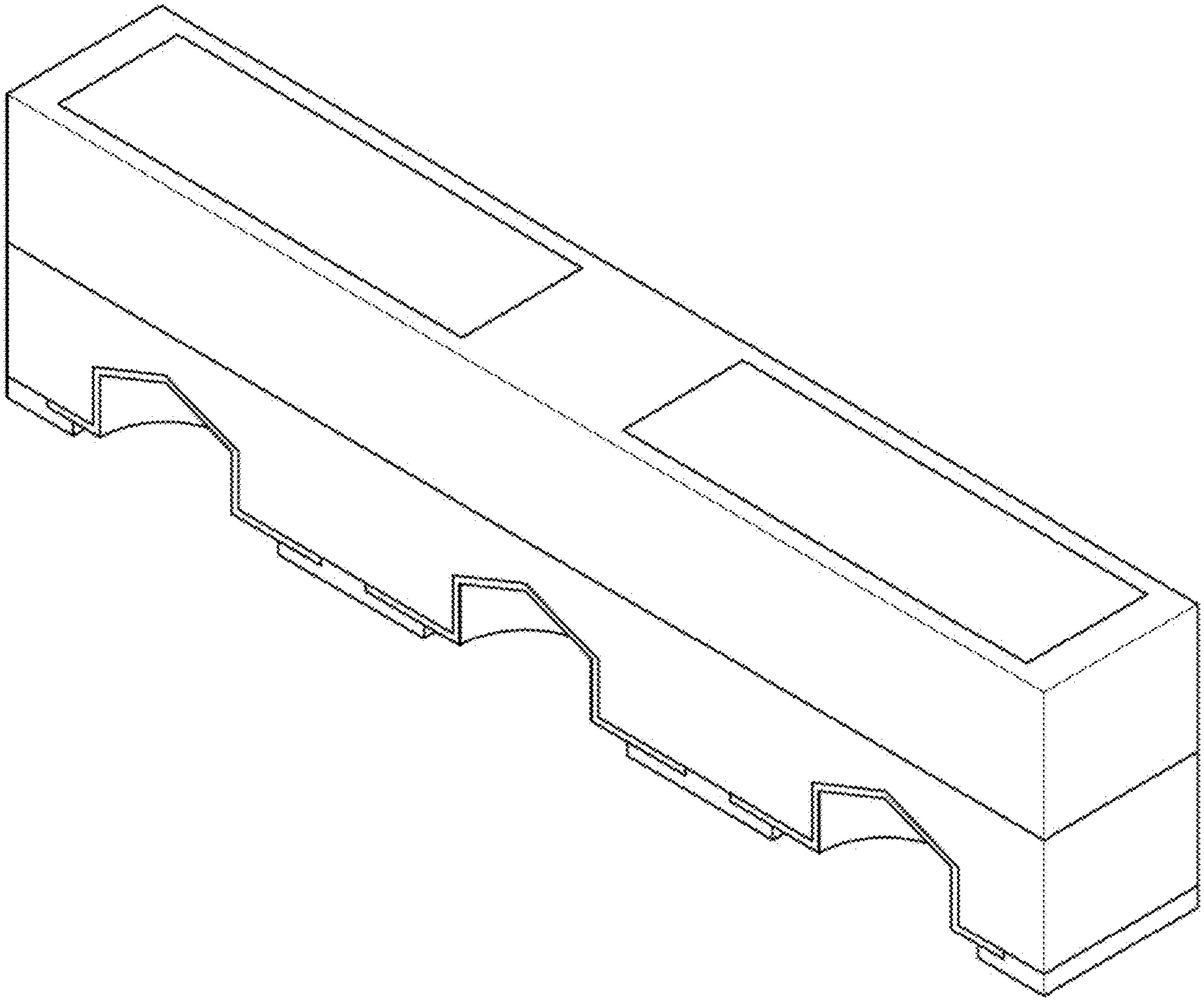

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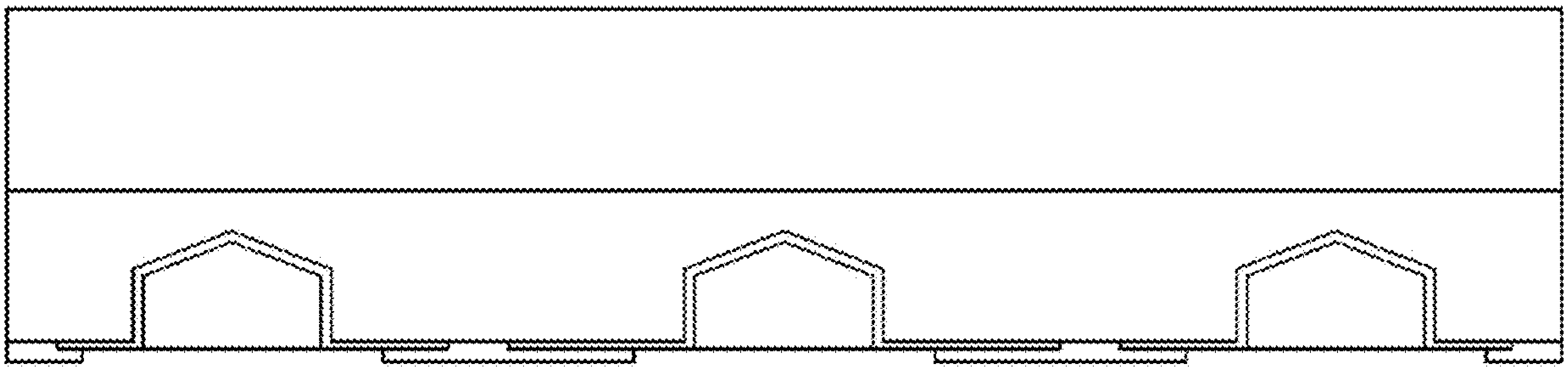

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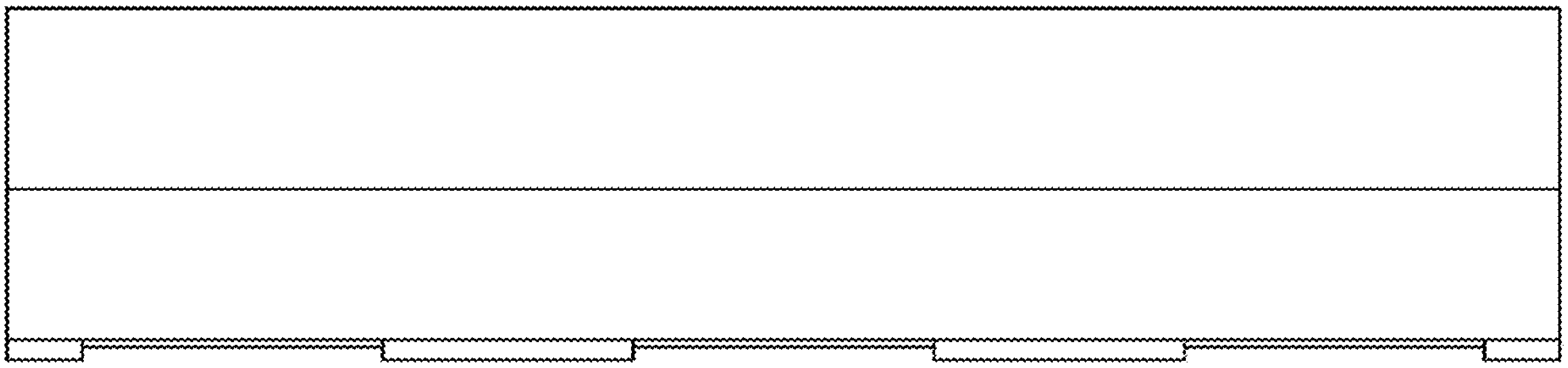

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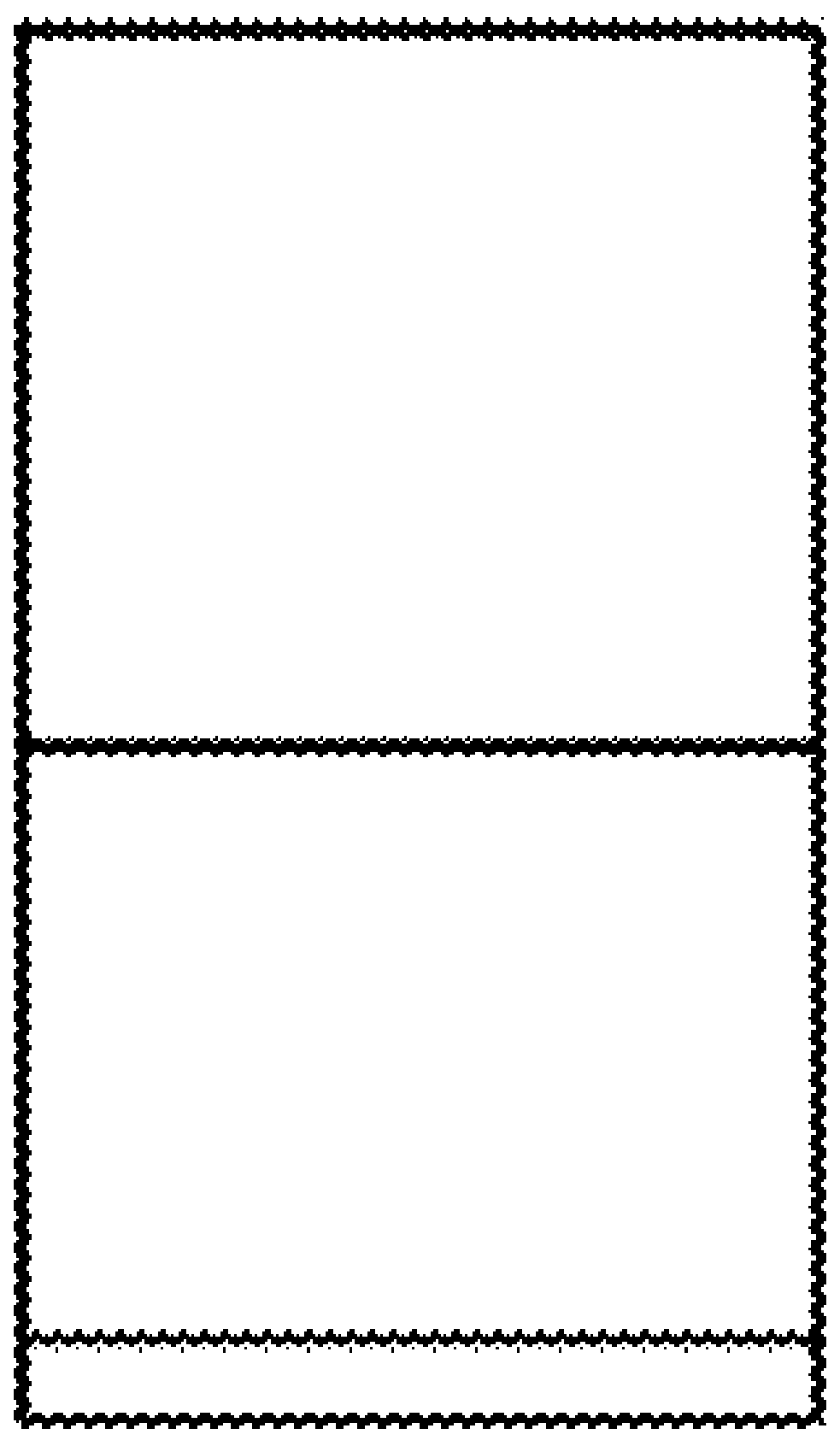

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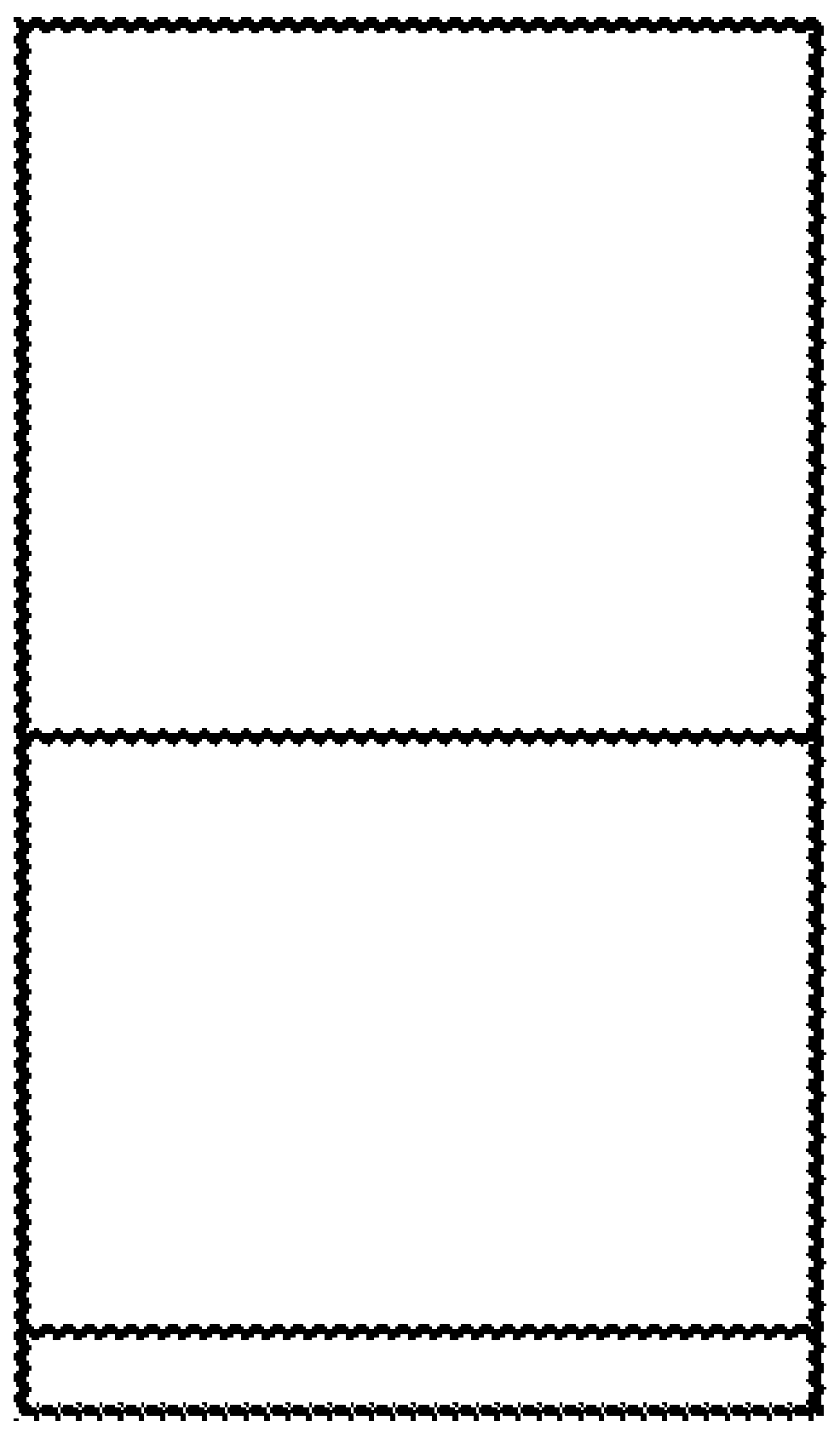

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